2274000-1 <

TE Internal #: 2274000-1 SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 32 Gb/s, EMI Springs, zSFP+ Thermally Enhanced, With Lightpipe, 1 x 1, Dual Round, Standard

View on TE.com >



Connectors > Pluggable IO Connectors & Cages > SFP, SFP+ & zSFP+ > zSFP+ Cage Assembly: EMI Springs



Pluggable I/O Product Type: Cage Assembly Data Rate (Max): 32 Gb/s EMI Containment Feature Type: EMI Springs Pluggable I/O Applications: zSFP+ Thermally Enhanced Lightpipe Options: With Lightpipe All zSFP+ Cage Assembly: EMI Springs (25)

Features

Product Type Features

Form Factor

zSFP+

Cinal

Cage Туре	Single		
Pluggable I/O Product Type	Cage Assembly		
Lightpipe Options	With Lightpipe		
Connector System	Cable-to-Board		
Sealable	No		
Connector & Contact Terminates To	Printed Circuit Board		
Configuration Features			
Port Matrix Configuration	1 x 1		
Lightpipe Configuration	Dual Round		
Lightpipe Style	Standard		
Lightpipe Profile	Standard		
Number of Ports	1		
Electrical Characteristics			
Data Rate (Max)	32 Gb/s		
Termination Features			

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 32 Gb/s, EMI Springs, zSFP+ Thermally Enhanced, With Lightpipe, 1 x 1, Dual Round, Standard



Termination Post & Tail Length	3 mm[.118 in]	
Termination Method to Printed Circuit Board	Through Hole - Press-Fit	
Mechanical Attachment		
Connector Mounting Type	Board Mount	
Housing Features		
Cage Material	Nickel Silver Alloy	
Dimensions		
PCB Thickness (Recommended)	1.5 mm[.059 in]	
Usage Conditions		
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]	
Operation/Application		
Heat Sink Compatible	No	
For Use With Pluggable I/O Products	zSFP+ SMT Connector	
Pluggable I/O Applications	zSFP+ Thermally Enhanced	
Circuit Application	Signal	
Packaging Features		
	–	

Packaging Method

Other

EMI Containment Feature Type

EMI Springs

Tray

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not applicable for solder process capability

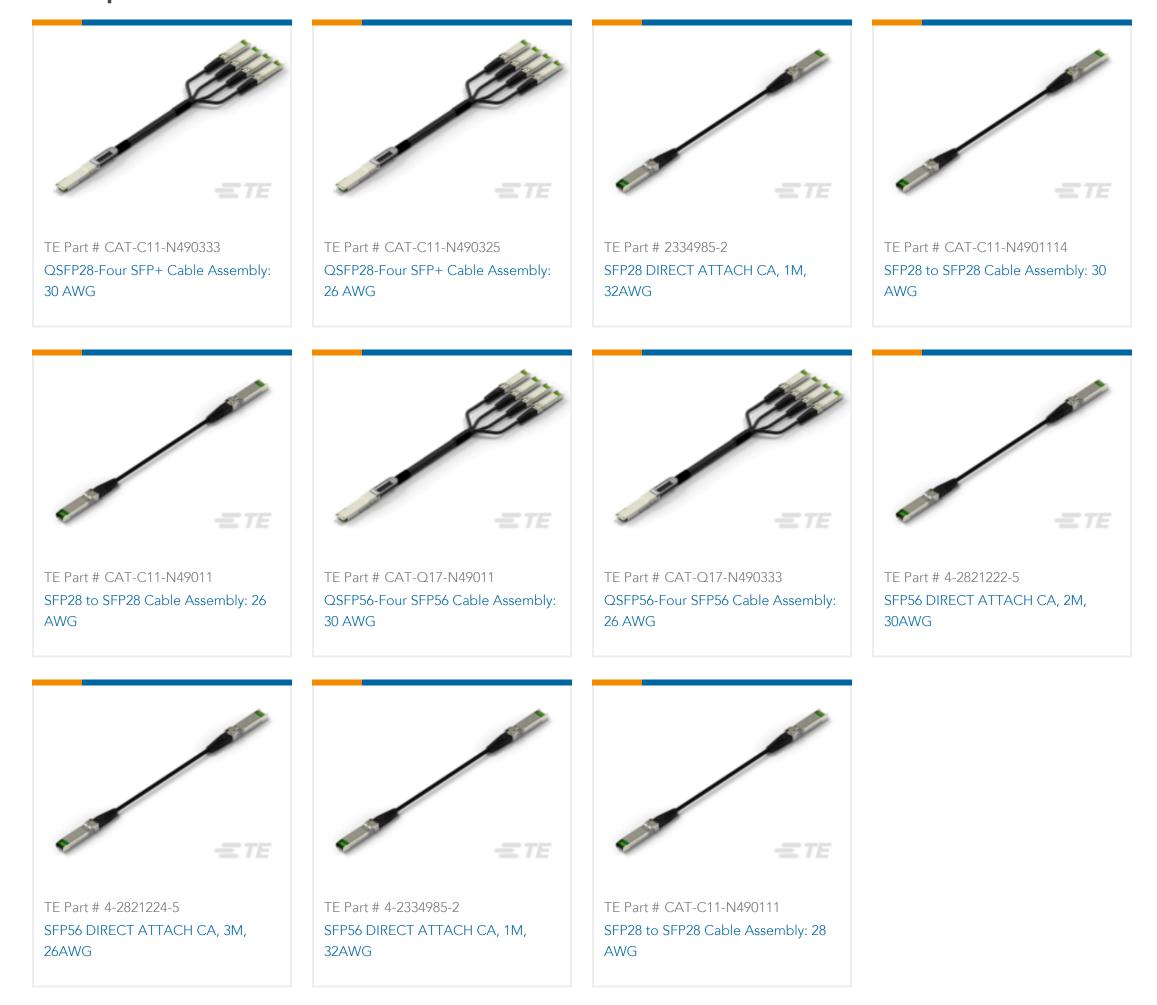
SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 32 Gb/s, EMI Springs, zSFP+ Thermally Enhanced, With Lightpipe, 1 x 1, Dual Round, Standard



Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Customers Also Bought

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 32 Gb/s, EMI Springs, zSFP+ Thermally Enhanced, With Lightpipe, 1 x 1, Dual Round, Standard



		TE	ETE
TE Part #2170088-1 ZSFP+ Connector,30u"	TE Part #1761394-1 DUST COVER, SFP, GANGED & STACKED	TE Part #1932626-1 MJ,10MM,8P,BEZEL PNL TABS,SN	TE Part #1761013-3 SFP 1X6 LIGHT PIPE ASSY
TE Part #1-2835340-0 FOSM GLARO LEAD 4.8 MM FXS MINI 10M	TE Part #1554570-2 MODULE FEMALE GUIDE, UNIVERSAL POWER	TE Part #1554570-3 MODULE FEMALE GUIDE, UNIVERSAL POWER	TE Part #1746986-2 GROUND RETURN LOWER SHIELD TYPE B,PB-FRE
TE Part #2-2835340-0 FOSM GLARO LEAD 4.8 MM FXS MINI 20M	TE Part #353830-7 040 III HD 72POS CAP ASSY H TIN		

Documents

Product Drawings ZSFP+ 1X1 CAGE ASSEMBLY PRESSFIT WITH LP

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2274000-1_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2274000-1_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2274000-1_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

C For support call+1 800 522 6752

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 32 Gb/s, EMI Springs, zSFP+ Thermally Enhanced, With Lightpipe, 1 x 1, Dual Round, Standard



zSFP+ Interconnect Brochure

English

Product Specifications

Application Specification

English

Product Environmental Compliance

Product Compliance

English

Product Compliance

English